ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® International and Pa	IPC, Bannock	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration	ation of the second	the substances basses all lowe	within the er level mate	manufactur erials for wl	er listed ite hich the ma	em. Note: inufactur	if the item is an as er has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Tyj http://www.ipc.org/IPC-175x Distribut				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Information															
Company name*	Company un	Company unique ID			Unique ID Authority					Response Date*					
onsemi											2024-04-19				
			itle - Contact			Phone - Contact*					Email - Contact*				
Product-Env-Stewards Prod			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title -			Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Requester Item Number	Requester Item Number Mfr Iter		m Number Mfr Item Name			Effective Date Version Manufacturing		ing Site	W	veight*	UOM	Unit Type			
	NCV77	NCV7726DQAR2G Au		Automotive Driver		2024-04-19 PHC		PHG		1	58.51	mg	Each		
Ianufacturing Proccess Informa	ation						•							l	
Terminal Plating / Grid Array M	Iaterial [Ferminal Base	Alloy	J-STD-020 MSL Rating		Peak Process Body Temper		dy Temperatu	ture Max Time at Peak Tem		Temperatu	erature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 2		2		260		C	30		second	seconds 3			
omments															
TTENTION: MSL 2 Rated item requir	es Dry Pack (after electrical	test)												
or more information regarding materia	l composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.91	mg	Supplier	Silicon (Si)	7440-21-3		5.91	mg
Die Attach	1.2	mg	Supplier	Silver (Ag)	7440-22-4		0.9	mg
			Supplier	Epoxy resins	129915-35-1		0.3	mg
Lead Frame	60.56	mg	Supplier	Zinc (Zn)	7440-66-6		0.0606	mg
			Supplier	Iron (Fe)	7439-89-6		1.3929	mg
			Supplier	Copper (Cu)	7440-50-8		59.046	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0606	mg
Mold Compound-Black	99.39	mg		Epoxy resin	proprietary data		7.4543	mg
			Supplier	Phenolic Resin	Proprietary Data		2.4848	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		7.4543	mg
			Supplier	Carbon Black (C)	1333-86-4		0.497	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		81.4998	mg
Plating	0.47	mg	Supplier	Palladium (Pd)	7440-05-3		0.0113	mg
			В	Nickel (Ni)	7440-02-0		0.4136	mg
			Supplier	Gold (Au)	7440-57-5		0.0451	mg
Vire Bond - Au	0.98	mg	Supplier	Gold (Au)	7440-57-5		0.98	mg